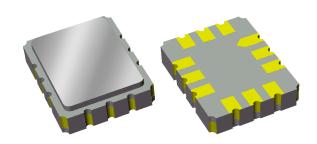


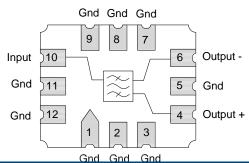
Applications

- General Purpose Wireless
- Wireless Infrastructure
- 3G, 4G, Multistandard



Functional Block Diagram SE/Bal

Top view

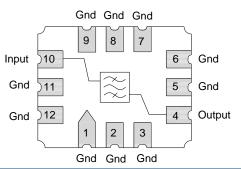


Product Features

- Usable bandwidth 60 MHz
- Low loss
- High attenuation
- Low EVM
- Single-Balanced or Single-Single ended operation
- Ceramic Surface Mount Package (SMP)
- Small Size: 7.01 x 5.51 x 1.70 mm
- Hermetic RoHS compliant, Pb-free

Functional Block Diagram SE/SE

Top view



Pin Configuration Pin # SE/SE Description 10 Input 4 Output 6 Ground 1,2,3,5,7,8,9,11,12 Case Ground

| Pin # SE/BAL | Description | |
|---------------------|-------------|--|
| 10 | Input | |
| 4 | Output + | |
| 6 | Output - | |
| 1,2,3,5,7,8,9,11,12 | Case Ground | |

General Description

The 856731 is a high performance IF SAW filter developed for 4G and Multistandard infrastructure applications.

It features low loss coupled with excellent attenuation, and is designed to be used with multiple impedance values and configurations. The filter is developed for excellent in-band characteristics in order to minimize system bit-error rates.

This device is RoHS compliant and Pb-free.

Ordering Information

| Part No. | Description | |
|------------|------------------|--|
| 856731 | packaged part | |
| 856731-EVB | evaluation board | |

Standard T/R size = 3000 units/reel.



Specifications

Electrical Specifications (1, 2)

Specified Temperature Range: (3) -40 to +85 °C

| Parameter (4) | Conditions | Min | Typical (5) | Max | Units |
|---------------------------|-----------------|-------|-------------|-------|--------|
| Center Frequency | | - | 192 | - | MHz |
| Insertion Loss | at 192 MHz | - | 13.5 | 14.5 | dB |
| Lower 3dB Bandedge (7) | | - | 156.2 | 160.7 | MHz |
| Upper 3dB Bandedge (7) | | 223.3 | 227.9 | - | MHz |
| Amplitude Variation (6) | 162 – 222 MHz | - | .5 | 1.0 | dB p-p |
| Group Delay Variation (6) | 162 – 222 MHz | - | 46 | 70 | ns p-p |
| Relative Attenuation (7) | 10.0 – 105 MHz | 45 | 53 | - | dB |
| | 105 – 132 MHz | 40 | 44 | - | dB |
| | 132 – 148 MHz | 38 | 42 | - | dB |
| | 238.5 – 245 MHz | 40 | 45 | - | dB |
| | 245 – 300 MHz | 40 | 49 | - | dB |
| | 300 – 455 MHz | 45 | 56 | - | dB |
| | 455 – 555 MHz | 43 | 46 | _ | dB |
| | 555 – 705 MHz | 50 | 55 | - | dB |
| | 705 – 1000 MHz | 60 | 71 | - | dB |
| Input/Output Return Loss | 162 – 222 MHz | 4.0 | 5 | - | dB |
| Source Impedance (SE) (8) | | - | 50 | - | Ω |
| Load Impedance (SE) (8) | | - | 50 | - | Ω |
| Load Impedance (Bal) (8) | | - | 150 | - | Ω |

Notes:

- 1. All specifications are based on the TriQuint schematic for the main reference designs shown on page 3 and 5
- 2. An external impedance matching network with ±2% tolerance will be necessary to achieve the proposed specifications
- 3. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature
- 4. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances

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- 5. Typical values are based on average measurements at room temperature
- 6. These Variations are defined as the difference between the lowest loss and the highest loss within the defined frequency points
- 7. Relative to insertion loss at center frequency
- 8. This is the optimum impedance in order to achieve the performance shown

Absolute Maximum Ratings

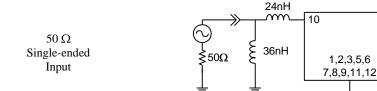
| Parameter | Rating |
|---|---------------|
| Operating Temperature | -40 to +85 °C |
| Storage Temperature | -40 to +85 °C |
| Input Power (at $+55^{\circ}$ C for $> 29,500$ hours max) | +15 dBm |

Operation of this device outside the parameter ranges given above may cause permanent damage.



Reference Design – 50Ω SE Input, 50Ω SE Output

Schematic

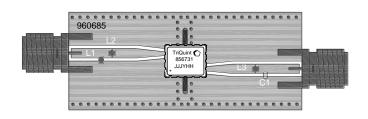


 $\begin{array}{c} 50~\Omega\\ Single-ended\\ Output \end{array}$

Notes:

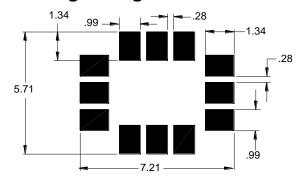
1. Actual matching values may vary due to PCB layout and parasitic

PC Board



Mounting Configuration

\$50Ω



Notes:

Top, middle & bottom layers: 1 oz copper Substrates: FR4 dielectric, .031" thick

Finish plating: Nickel: 3-8µm thick, Gold: .03-.2µm thick

Hole plating: Copper min .0008µm thick

Notes:

62nH

18pF

- 1. All dimensions are in millimeters.
- 2. This footprint represents a recommendation only.

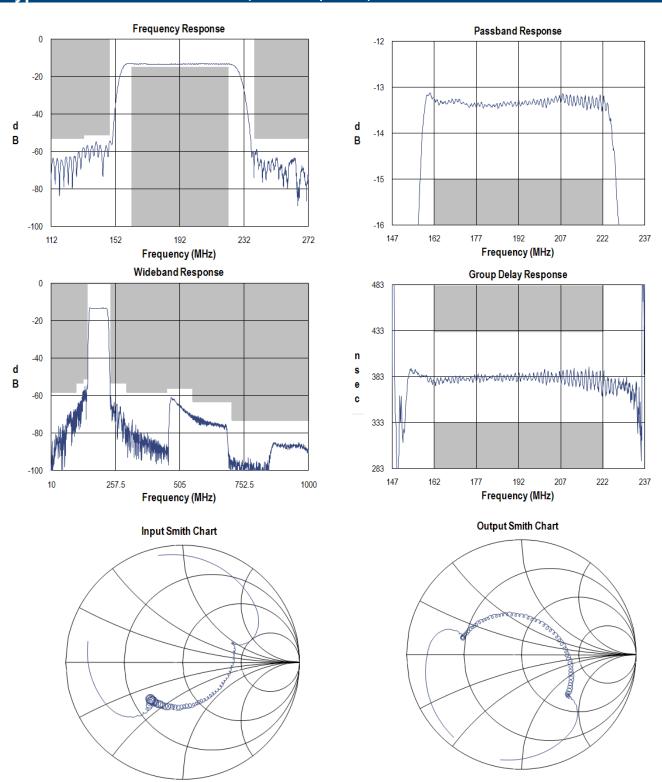
Bill of Material

| Reference Desg. | Value | Description | Manufacturer | Part Number |
|-----------------|-------|---------------------------|--------------------|-------------------|
| L1 | 36nH | Coil Wire-wound, 0603, 5% | MuRata | LQW18AN36NJ00 |
| L2 | 24nH | Coil Wire-wound, 0603, 5% | MuRata | LQW18AN24NJ00 |
| L3 | 62nH | Coil Wire-wound, 0603, 5% | MuRata | LQW18AN62NJ00 |
| C1 | 18pF | Chip Ceramic, 0603, 5% | MuRata | GRM1885C1H180JA01 |
| SMA | N/A | SMA connector | Johnson Components | 142-0701-801 |
| PCB | N/A | 3-layer | multiple | 960686 |

Connecting the Digital World to the Global Network



Typical Performance SE/SE(at room temperature)



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 150Ω

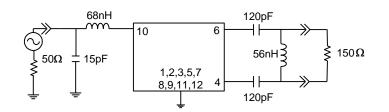
Balanced

Output

Reference Design – 50Ω SE Input, 150Ω BAL Output

Schematic

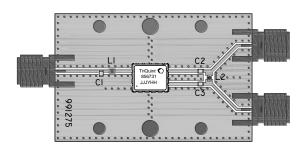
50 Ω Single-ended Input



Notes:

2. Actual matching values may vary due to PCB layout and parasitic

PC Board



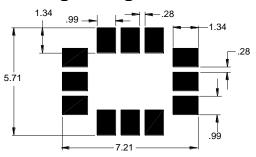
Notes:

Top, middle & bottom layers: 1 oz copper Substrates: FR4 dielectric, .031" thick

Finish plating: Nickel: 3-8µm thick, Gold: .03-.2µm thick

Hole plating: Copper min $.0008\mu m$ thick

Mounting Configuration



Notes:

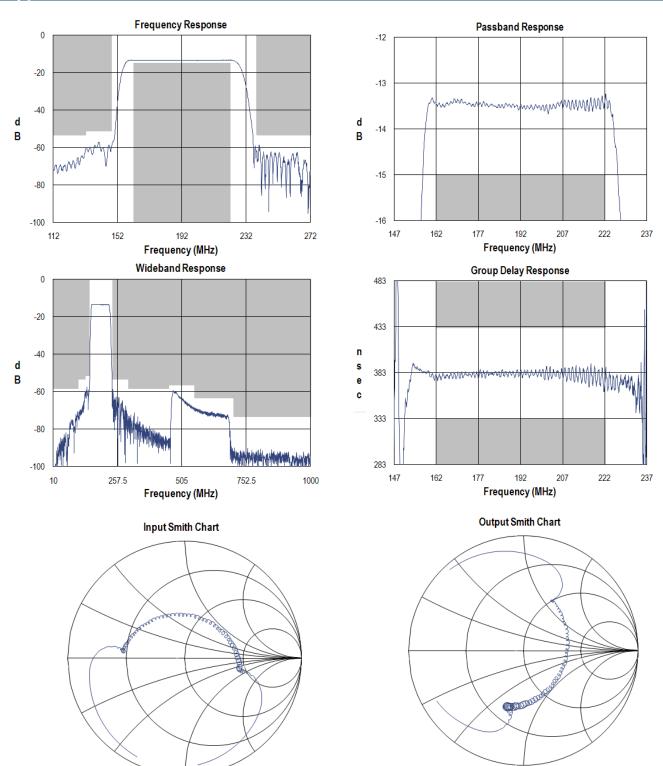
- 3. All dimensions are in millimeters.
- 4. This footprint represents a recommendation only.

Bill of Material

| Reference Desg. | Value | Description | Manufacturer | Part Number |
|-----------------|-------|---------------------------|------------------|-------------------|
| L1 | 68nH | Coil Wire-wound, 0603, 5% | MuRata | LQW18AN68NJ00 |
| L2 | 56nH | Coil Wire-wound, 0603, 5% | MuRata | LQW18AN56NJ00 |
| C1 | 15pF | Chip Ceramic, 0603, 5% | MuRata | GRM1885C1H150JA01 |
| C2 | 120pF | Chip Ceramic, 0603, 5% | MuRata | GRM1885C1H121JA01 |
| C3 | 120pF | Chip Ceramic, 0603, 5% | MuRata | GRM1885C1H121JA01 |
| SMA | N/A | SMA connector | Radiall USA Inc. | 9602-1111-018 |
| PCB | N/A | 3-layer | multiple | 991275 |



Typical Performance SE/BAL (at room temperature)

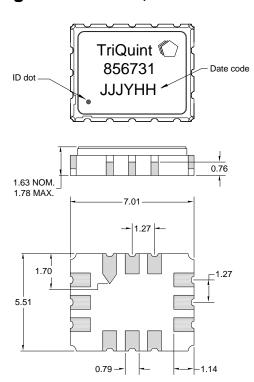


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Mechanical Information

Package Information, Dimensions and Marking



Package Style: SMP-28B

Dimensions: 7.01 x 5.51 x 1.63 mm

Body: Al_2O_3 ceramic Lid: Kovar, Ni plated

Terminations: Au plating 0.5 - 1.0μm, over a 2-6μm Ni

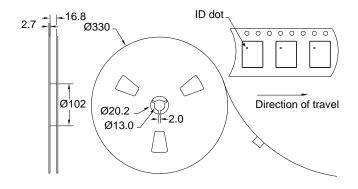
plating

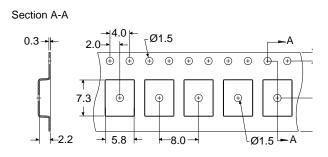
All dimensions shown are nominal in millimeters All tolerances are $\pm 0.15 mm$ except overall length and width $\pm 0.10 mm$

The date code consists of: day of the current year (Julian, 3 digits), Y = last digit of the year (1 digit), and HH = hour (2 digits)

Tape and Reel Information

Standard T/R size = 3000 units/reel. All dimensions are in millimeters







Product Compliance Information

ESD Information



Caution! ESD-Sensitive Device

ESD Rating: 1A

Value: Passes ≥ 400 V min.

Test: Human Body Model (HBM)

Standard: JEDEC Standard JESD22-A114

ESD Rating: B

Value: Passes ≥ 250 V min. Test: Machine Model (MM)

Standard: JEDEC Standard JESD22-A115

MSL Rating

Devices are Hermetic, therefore MSL is not applicable

Solderability

Compatible with the latest version of J-STD-020, lead free solder, 260° C

Refer to **Soldering Profile** for recommended guidelines.

This part is compliant with EU 2002/95/EC RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).

This product also has the following attributes:

- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A $(C_{15}H_{12}Br_4O_2)$ Free
- PFOS Free
- SVHC Free

Contact Information

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Email: flapplication.engineering@tqs.com

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